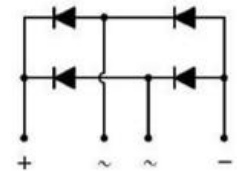
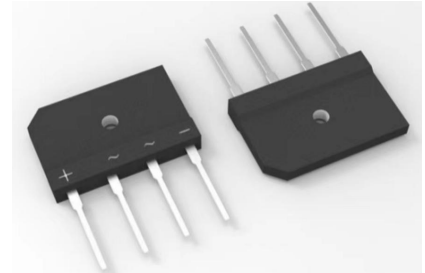


Features

- ◆ Glass Passivated Die Construction
- ◆ High Case Dielectric Strength of 2500V RMS
- ◆ Low Reverse Leakage Current
- ◆ Surge Overload Rating to 350A Peak
- ◆ Ideal for Printed Circuit Board Applications
- ◆ Lead Free Finish; RoHS Compliant

Mechanical Data

- ◆ Case: GBJ
- ◆ Case Material: Molded Plastic. UL Flammability Classification 94V-0
- ◆ Moisture Sensitivity: Level 1 per J-STD-020
- ◆ Terminals: Plated Leads, Solderable per MIL-STD-202, Method 208
- ◆ Lead Free Plating (Tin Finish).
- ◆ Polarity: Molded on Body



Dimensions (GBJ)

Symbol	Dimension (mm)	
	Min.	Max.
A	29.70	30.30
B	19.70	20.30
C	17.00	18.00
D	3.80	4.20
E	7.30	7.70
G	9.80	10.20
H	2.00	2.40
I	0.90	1.10
J	2.30	2.70
K	3.0×45°	
L	4.40	4.80
M	3.40	3.80
N	3.10	3.40
P	2.50	2.90
R	0.60	0.80
S	10.80	11.20

Maximum Ratings and Thermal Characteristics($T_A=25^{\circ}\text{C}$ unless otherwise noted)

Parameter		Symbol	GBJ 2502	GBJ 2504	GBJ 2506	GBJ 2508	GBJ 2510	Unit
Peak Repetitive Reverse Voltage		V _{RRM}	200	400	600	800	1000	V
Non-Repetitive Peak Reverse Voltage		V _{RSM}	300	500	700	900	1100	V
Maximum average forward output rectified current	T _C =100℃	I _{F(AV)}	25					A
Rating for Fusing (t < 8.3ms)		I ² t	500					A ² s
Non-Repetitive Peak Forward Surge Current 8.3 ms Single Half Sine-Wave Superimposed on rated Load		I _{FSM}	350					A
Maximum thermal resistance per leg		R _{θJA} (Note1)	22					℃/W
		R _{θJC} (Note2)	1.0					
Operating and Storage Temperature Range		T _J , T _{STG}	-55~+150					℃

Electrical Characteristics ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

Parameter		Symbol	Value	Unit
Maximum Instantaneous Forward Voltage per leg	$I_{FM}=12.5\text{A}$	V_F	1.1	V
Peak Reverse Current at Rated DC Blocking Voltage	$T_A=25^{\circ}\text{C}$	I_R	5.0	μA
	$T_A=125^{\circ}\text{C}$		500	

Notes : 1.Junction to ambient without heatsink.

2.Junction to case with heatsink.

Ratings and Characteristic Curves (T_A=25°C unless otherwise noted)

Figure 1. Forward Current Derating Curve

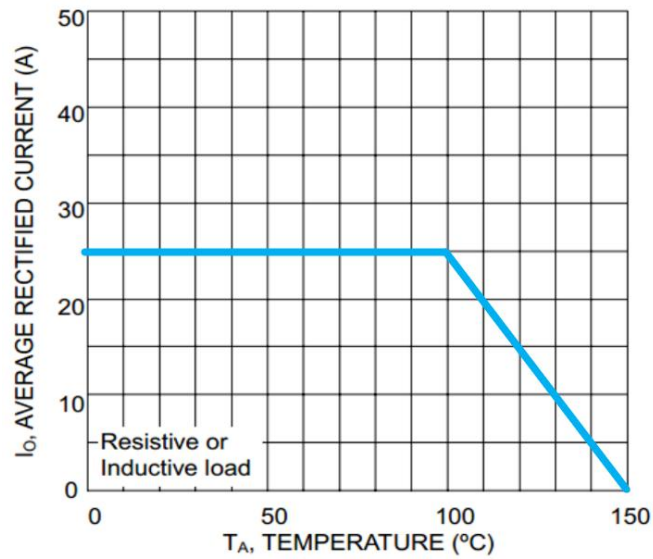


Figure 2. Typical Forward Characteristics (per element)

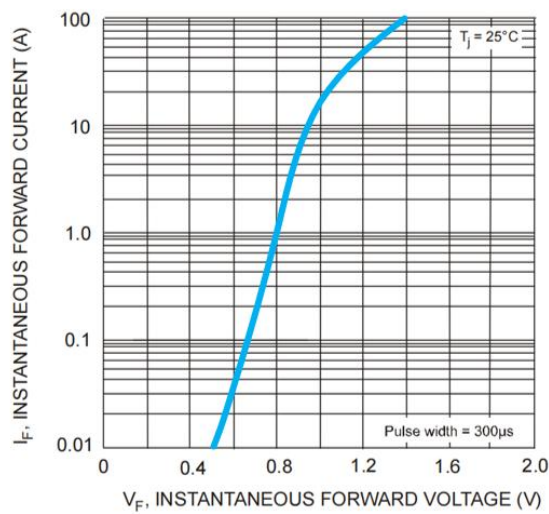


Figure 3. Maximum Non-Repetitive Surge Current

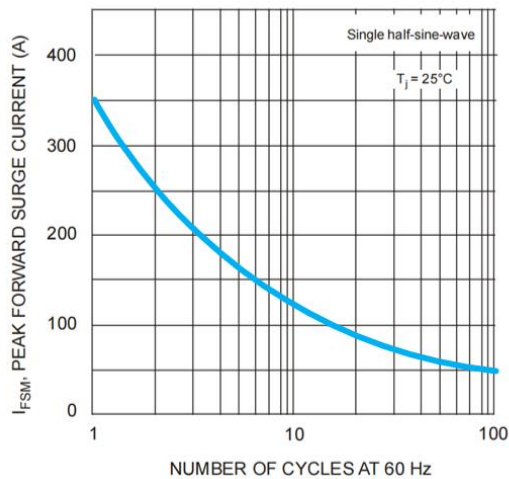


Figure 4. Typical Total Capacitance, Per Element

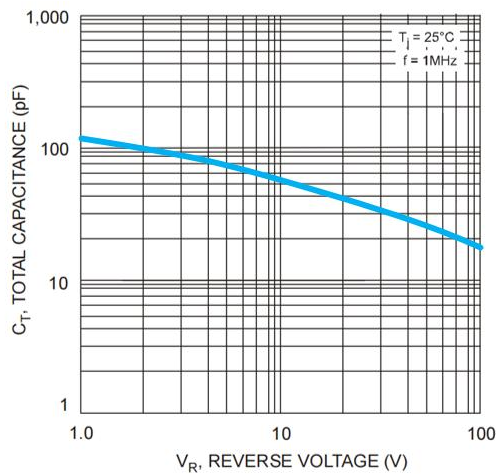
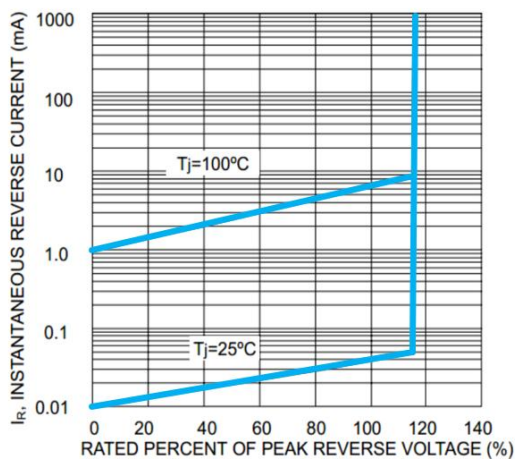
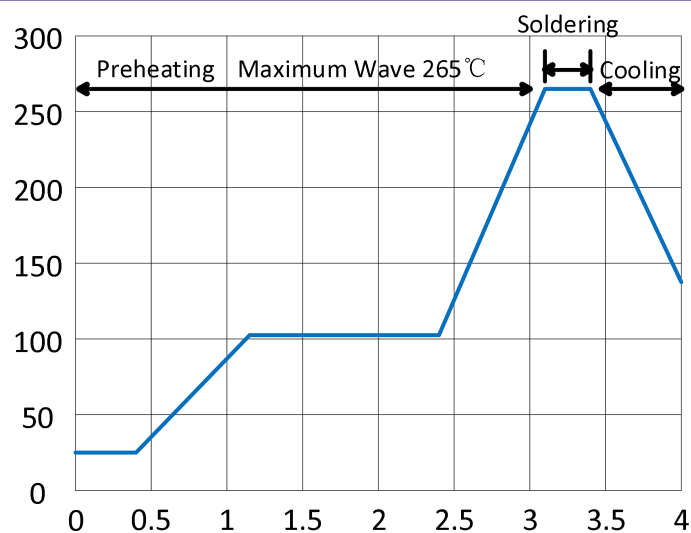


Figure 5. Typical Reverse Characteristics



Wave Soldering Parameters



Reflow Condition	Lead-free Assembly
Peak Temperature	265°C
Dipping Time	10 seconds
Soldering	1 time